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U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM 10075226	FILING DATE 02/15/2002	CLASS 174	SUBCLASS 52.4	GAU 2831	EXAMINER <del>OL+VA</del> N80
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\*\*CONTINUING DATA VERIFIED:

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\*\*FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		BHT-3183-39
Verified and Acknowledged Examiners's initials <u>HVN</u>		
TITLE : Thermally enhanced semiconductor build-up package		

U.S. DEPT. OF COMM. / PAT. & TM. PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
Assistant Examiner		Total Claims	Print Claim for O.G.
Primary Examiner		Sheets Drwg.	Print Fig.
Application Examiner		Prepared for Issue	
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